

Docket No.: 27-010  
Express Mail Label No.: EV129577441US

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: Kambhampati Ramakrishna : Confirmation No.:  
Serial No.: : Art Unit:  
Filed: June 25, 2003 : Examiner:  
For: SEMICONDUCTOR :  
PACKAGE FOR A  
LARGE DIE

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

Sir/Madam:

The following Preliminary Amendment and Remarks are submitted within 3 months of the filing date or before the first office action, following the revised amendment format as set forth in the Revised Notice "Amendments May Now Be Submitted in Revised Format". After this introductory section, there are Amendments to the Specification and then Remarks, each starting on a separate page.

Amendments to the Specification consist of amendments to the paragraphs on page 11, line 11 and page 12, line 24.

## AMENDMENTS TO THE SPECIFICATION

- Please amend the paragraph which begins on page 11, line 11, as follows:

It will be apparent to one skilled in the art that positioning of the second contact pad 809 beneath the surface of the large die 712 results in a more compact arrangement of contact pads than if the semiconductor package 700 of the present invention was not used. If the permissible die size is limited by the size of the die pad, the ~~solder balls~~ contact pads are arranged outside the edges of the die.

- Please amend the paragraph, which begins on page 12, line 24, as follows:

Referring now to FIG. 17 therein is shown the structure of FIG. 16 with the large die 1312 attached to the spacer 1310 using a second adhesive layer 1700. The large die 1312 at least partially overlaps the contact pad 1412 attached to the inner bonding finger 1409 and also overlaps the inner edge of the outer bonding finger 1408 ~~and the inner edge of the inner bonding finger 1409~~. The large die 1312 has a bottom surface 1702 that is positioned above the outer bonding finger 1408 and the inner bonding finger 1409. Accordingly, the use of the spacer 1310 enables usage of the large die 1312.